









Product Catalog



◆ ELSOLD® Table of contents

| ELSOLD® | Editorial | | Page 01 |
|---------|---------------------------------------|---|----------------|
| ELSOLD® | Service and Certification | | Page 02 |
| ELSOLD® | Product Range | | Page 03 |
| ELSOLD® | Cored Solder Wires with lead | • | Page 04 |
| ELSOLD® | Cored Solder Wires, lead free | • | Page 05 |
| ELSOLD® | Cored Solder Wires, lead free C3 Plus | • | Page 06 |
| ELSOLD® | Bars and Ingots with lead | • | Page 07 |
| ELSOLD® | Bars and Ingots, lead free | • | Page 08 |
| ELSOLD® | Solid Wires with lead | • | Page 09 |
| ELSOLD® | Solid Wires, lead free | • | Page 10 |
| ELSOLD® | Solder Paste with lead | | Page 11 |
| ELSOLD® | Solder Paste, lead free | | Page 12 |
| ELSOLD® | Solder Paste, lead free AP-40 | | Page 13 |
| ELSOLD® | Flux - Tacky Flux | = | Page 14 |
| ELSOLD® | Flux | | Page 15 |
| ELSOLD® | Rework Flux | = | Page 16 |
| ELSOLD® | Flux Solar Industry | | Page 18 |
| ELSOLD® | Cleaner and Accessories | | Page 19 |
| ELSOLD® | Order form | | Page 20 |



ELSOLD® Editorial

ELSOLD GmbH & Co. KG is one of the world's leading manufacturers of lead, tin and corresponding alloys. Experts and customers appreciate our company as a competent and reliable partner.

Today the Goslar site, where lead ore has been mined for more than 1000 years, offers a unique wealth of expert metallurgical knowledge and Know-How.

As an established result, our business unit ELSOLD® with more than 50 years experience has the largest scope of innovative soldering products worldwide. We supply customers throughout the electronic and solar industries

ELSOLD® brand innovative soldering products fulfil the highest demands in modern electronic connection technology. Even in the initial design stages, we provide for all legal requirements, engineer and international standards.

In order to expand our international top position, we are in close contact with our customers: knowing their needs enables us to optimize our products. We combine traditional knowledge and Know-How with the latest scientific expertise.

Our ambitions for the years coming are quite clear: ELSOLD® will continue to develop and produce top quality innovative soldering products, customized to new technologies and production technique.

We are a company with a long tradition, we think local and act global. Our focus with all our activities is a long-term relationship with customers, partners and employees.

Join us into a future where ever growing challenges inspire top quality products.



ELSOLD® Service | ELSOLD® Certification

Delivery Service

ELSOLD®'s entire product range is produced in Goslar. This results in short delivery times allowing us to provide JIT deliveries on special customer request.

Technical support and application advice

In order to assure the quality of our customers finished products, we attach great importance to providing advice and support. Selecting the right soldering products and processing parameters with regard to the customers' production equipment and environmental issues is crucial for us.

Change-over to lead-free materials

The change-over to lead-free materials creates costs and triggers questions about the reliability and difficulties of lead-free material. We are pleased to offer our experience from successful change-over processes already implemented in our customer base. Join us as partner when it comes to a need of competent answers to commercial and technical queries.

Internet Service

Download technical data sheets for all important solder products from our website **www.elsold.de**

Solder bath analysis

ELSOLD® analyses submitted samples. The customer is informed about the level of impurities with a recommendation as how to proceed for further operation.

Disposal of used soft soldering material

We dispose of your unusable old material (like "Dross") at fair conditions.

ELSOLD® Certification

ELSOLD® production process complies with the quality management standard ISO TS 16949. Certification for this comprehensive directive for the automotive industry was achieved in September 2007 and is still valid.

Certificate - Registration - No. 236773QM08

ELSOLD® products fulfil the standards ISO 9453:2006, DIN EN 29453 and 29454, DIN EN 61190 1-1 to 1-3, the key international standards and the ELSOLD® works standards which are not covered by any official standard.

Selected ELSOLD® soft solders fulfil the ESA soldering standard ECSS-Q-70-71A. All spacecraft launched into space by ESA (European Space Agency) are soldered with ELSOLD® soft solders because of their high quality, high reliability and long service life.

Certificate no. ECSS – Q – 70 – 71A Rev. 1.

Contact: Phone +49 (0) 53 21 754-229

Email info@elsold.com Internet www.elsold.com



ELSOLD® Cored Solder Wires - general information

Cored solder wire – the oldest solder medium – has been used for many years in the electronic industry. Cored solder wire permits the simultaneous application of solder and flux to the soldering point. Despite development of solder paste which serves the same purpose, cored solder wire has defended its position. It is still preferred for applications such as manual and repair soldering processes and automatic soldering (robot process).

ELSOLD® cored solder wire is available in many types and

is unchallenged because of its variety.

Besides the purity of the base metals, the particular innovation is the constant adaptation of solder paste composition to production parameter and process. Rosin and activator must be adapted to higher or changed process temperatures.

ELSOLD® produces top quality Cored Solder wires by choosing suitable flux constituents along with strictly monitored production conditions.

ELSOLD® Cored Solder Wired – Flux types

| Flux type | Application |
|----------------|--|
| A3 | For applications requiring active flux effective on brass, nickel, bronze |
| C3 | Halide free flux for all electronic applications |
| E1 | Extremely temperature stable and splatter-free |
| 3064 3064 BF | For difficult soldering processes, also effective on brass, nickel, bronze |
| Н | Based on carbamide, very effective flux without resin, e.g. for manufacture of transformers and capacitors |
| Т | For heavily oxidised surfaces, resin-free, halogen-activated. Used in the electric bulb industry |
| FS-28 | Strongly activated, halide-free flux for demanding solder work, reduced resin content and low residue |
| 105-19 | Resin-free, halogenated, very active, low residue |

The list above shows a selection of our most sought-after products.

Of course you can order your alloy with the flux you require.

For custom-made orders, the flux fraction can be selected from 0.5% to 4.5% in steps of 0.5%.

Special dimensions available on request

- Standard coil sizes: 0.10 kg / 0.25 kg / 0.50 kg / 1.00 kg
- Special coil sizes (e.g. 2.5 kg up to 20 kg) available on request
- All cored solder wires are available with a diameter of 0.3 mm upwards
- Diameters are subject to standard tolerances as per DIN 12224-1
- Single or multi-core possible



ELSOLD® Cored Solder Wires

ELSOLD® is one of the leading manufacturers of high quality solder products for all noted processes, including solar technology. ELSOLD® cored solder wires are available in a variety of alloys combined with highly efficient fluxes. The special combination of proven activators and first-class wetting properties guarantee the very best soldering quality in automatic and manual soldering processes. This also applies to soldering processes in solar technology.

ELSOLD® Cored Solder Wires with lead

| Alloy | Melting | Ø | Spool | Flu | ux | DIN EN | | Halide | No | Order |
|-------------|---------------|------|---------------|--------------|--------|--------|-----------|----------------|--------------|-----------|
| | Range [°C] | [mm] | sizes [kg] | -content [%] | - type | 29454 | 61190-1-1 | content [%] | Clean | number |
| Sn60Pb39Cu1 | 183-190 | 1.00 | 1 | 3.5 | А3 | 1.1.2 | ROH1 | 0.75 | \checkmark | EL01 1421 |
| Sn60Pb39Cu1 | 183-190 | 1.00 | 1 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL01 0913 |
| Sn60Pb39Cu1 | 183-190 | 2.00 | 1 | 3.5 | Н | 2.1.3 | ORM0 | 0 | \checkmark | EL01 1742 |
| Sn60Pb39Cu1 | 183-190 | 1.50 | 1 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | \checkmark | EL01 5103 |
| Sn60Pb39Cu1 | 183-190 | 1.00 | 0.50 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | \checkmark | EL01 5122 |
| Sn60Pb40 | 183-190 | 0.75 | 1 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | \checkmark | EL01 5101 |
| Sn60Pb40 | 183-190 | 0.75 | 1 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL01 2139 |
| Sn60Pb40 | 183-190 | 0.50 | 1 | 3.5 | А3 | 1.1.2 | ROH1 | 0.75 | \checkmark | EL01 2275 |
| Sn63Pb37 | 183 | 1.00 | 1 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL01 2483 |
| Sn63Pb37 | 183 | 1.00 | 1 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | \checkmark | EL01 5158 |
| Sn62Pb36Ag2 | 179 | 0.75 | 0.50 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | \checkmark | EL01 5224 |
| Sn60Pb36Ag4 | 178-180 | 1.00 | 1 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL01 3425 |
| Pb91Sn8Sb1 | 280-305 | 0.80 | 1 | 2.5 | C2 | 1.1.3 | ROM0 | 0 | \checkmark | EL01 2606 |
| Pb91Sn8Sb1 | 280-305 | 1.00 | 1 | 1.0 | FS-28 | 1.1.3 | ROL0 | 0 | ~ | EL01 4757 |

Picture: Cored Solder Wires with lead delivery forms













1000 g 500 g 250 g

500 g



Highlight

NEW! Lead-free Solder wire "E1" containing flux



- splatter-free
- longer holding time of soldering tip
- reduction of copper de-alloying
- for all soldering applications
- non-corrosive flux residues
- thermally stable flux
- excellent soldering properties
- fulfils all global standards



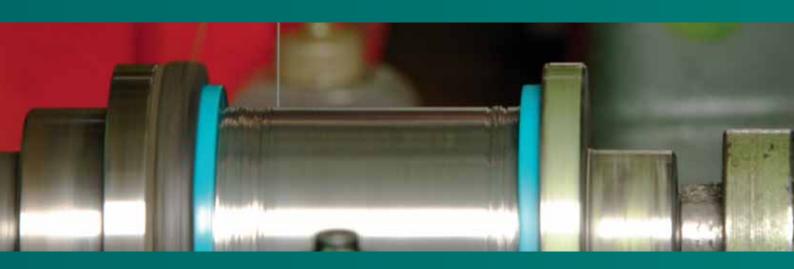
ELSOLD® Cored Solder Wires, lead-free

| Alloy | Melting | Ø | Spool | FI | џх | [| DIN EN | Halide | No | Order |
|------------------|---------------|------|---------------|------------------|--------|-------|-----------|----------------|--------------|-----------|
| | Range [°C] | [mm] | sizes [kg] | - content [%] | - type | 29454 | 61190-1-1 | content [%] | Clean | number |
| Sn99.3Cu0.7 | 227 | 1.00 | 1.00 | 2.2 | 3064BF | 1.1.2 | ROM1 | 1.20 | \checkmark | EL02 5283 |
| Sn99.3Cu0.7 | 227 | 0.75 | 1.00 | 2.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL02 5416 |
| Sn99.3Cu0.7 | 227 | 0.75 | 1.00 | 3.5 | А3 | 1.1.2 | ROH1 | 0.75 | ~ | EL02 0014 |
| Sn99.3Cu0.7 | 227 | 0.60 | 0.50 | 1.5 | 105-19 | 2.2.2 | ORM1 | < 2.00 | V | EL02 5399 |
| Sn99.3Cu0.7MA | 227 | 0.75 | 0.50 | 2.5 | E1 | 1.1.3 | ROM0 | 0 | ~ | EL02 0008 |
| Sn99.3Cu0.7MA | 227 | 0.50 | 1.00 | 2.5 | E1 | 1.1.3 | ROM0 | 0 | V | EL02 6102 |
| Sn97Cu3 | 230-250 | 2.00 | 3.50 | 2.0 | Т | 2.2.2 | ORM1 | < 2.00 | | EL02 6011 |
| Sn95Sb5 | 230-240 | 1.00 | 1.00 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | \checkmark | EL02 3466 |
| Sn97Ag3 | 221-230 | 1.00 | 1.00 | 2.2 | 3064BF | 1.1.2 | ROM1 | 1.20 | ~ | EL02 0010 |
| Sn96.5Ag3Cu0.5 | 217-219 | 1.00 | 1.00 | 2.2 | 3064BF | 1.1.2 | ROM1 | 1.20 | \checkmark | EL02 5444 |
| Sn96.5Ag3Cu0.5 | 217-219 | 1.00 | 1.00 | 2.5 | C3 | 1.1.3 | ROM0 | 0 | ~ | EL02 5545 |
| Sn96.5Ag3Cu0.5 | 217-219 | 0.30 | 0.25 | 2.5 | C3 | 1.1.3 | ROM0 | 0 | V | EL02 6046 |
| Sn95.8Ag3.5Cu0.7 | 217 | 1.00 | 1.00 | 3.5 | C3 | 1.1.3 | ROM0 | 0 | V | EL02 5508 |
| Sn95.8Ag3.5Cu0.7 | 217 | 0.75 | 1.00 | 2.2 | 3064 | 1.1.2 | ROM1 | 1.15 | V | EL02 5370 |

All lead-free alloys are available as ELSOLD® MA® (micro-alloyed)

Your advantages: • fine-grained structure facilitates visual inspection

- low de-alloying of copper allows lead-free tinning of thin wires and circuit paths, multiple joints and repairs
- Significant cost saving though low chemical attack on material soldering tips and equipment





"No-clean" Halide-free Flux Cored Solder wire "C3 Plus" Lead Free

- quick wetting
- low elastic residues
- non-corrosive flux residues
- short soldering time
- reduced copper erosion

- thermal stable flux
- fulfil all global standards
- for all soldering applications
- excellent solderability
- shiny solder joints

| Alloy | Melting | Fl | XL | DIN | EN | |
|------------------|---------------|-----------------|--------|-------|-----------|--------------|
| | Range [°C] | -content [%] | - type | 29454 | 61190-1-1 | No Clean |
| Sn99.3Cu0.7 | 227 | ** | C3+ | 1.1.3 | ROM0 | \checkmark |
| Sn97Cu3 | 230-250 | ** | C3+ | 1.1.3 | ROM0 | \checkmark |
| Sn95Sb5 | 230-240 | ** | C3+ | 1.1.3 | ROM0 | V |
| Sn97Ag3 | 221-230 | ** | C3+ | 1.1.3 | ROM0 | ~ |
| Sn96.5Ag3Cu0.5 | 217-219 | ** | C3+ | 1.1.3 | ROM0 | V |
| Sn95.8Ag3.5Cu0.7 | 217 | ** | C3+ | 1.1.3 | ROM0 | V |

The list above shows just a selection of our products.

Of course you can order your alloy with the flux you require. Special diameters available on request

**For custom-made orders, the flux fraction can be selected from 0.5% to 4.5% in steps of 0.5%.

- Standard coil sizes: 0.10 kg / 0.25 kg 0.50 kg / 1.00 kg
- Special coil sizes (e.g. 2.5 kg up to 20 kg) available on request
- All cored solder wires are available with a diameter of 0.3 mm upwards
- Diameters are subject to standard tolerances as per DIN 12224-1
- Single or multi-core possible

Picture: Cored Solder Wires lead free delivery forms





1000 g 500 g

250 g



ELSOLD® Bars and Ingots

Increasing miniaturisation, stricter requirements with regard to long-term reliability of complex electronic products, components and related extended performance features thereof make highest demands on soldering quality. ELSOLD® soft solders are therefore produced only from carefully selected

virgin-grade base metals. ELSOLD® soft solders cover the entire range of electronic applications: machine solders, high temperature solders, special solders (low-melting alloys, solders for static baths).

ELSOLD® Bars and Ingots with lead

| Alloy | Melting Range [°C] | Operation tem- perature [°C] | Delivery Form | Dimensions [mm] | Weight [ca. kg] | Order number |
|-------------------|-----------------------|---------------------------------|-----------------|-----------------|--------------------|--------------|
| Sn63Pb37P | 183 | 240-260 | Ingots | 50x20x490 | 4.0 | EL03 0129 |
| Sn63Pb37P | 183 | 240-260 | Triangular bars | 8/10x400 | 0.2 | EL03 0017 |
| Sn63Pb37P | 183 | 240-260 | Ingots | 50x18x600 | 4.5 | EL03 0133 |
| Sn63Pb37 | 183 | 240-260 | Ingots | 50x20x490 | 4.0 | EL03 0235 |
| Sn63Pb37 | 183 | 240-260 | Triangular bars | 8/10x400 | 0.2 | EL03 0393 |
| Sn60Pb40P | 183-190 | 240-260 | Triangular bars | 8/10x400 | 0.2 | EL03 0013 |
| Pb95Sn3Ag2 | 304-310 | > 450 | Triangular bars | 8/10x400 | 0.2 | EL03 0026 |
| Pb95Sn3Ag2P | 304-310 | > 450 | Triangular bars | 8/10x400 | 0.2 | EL03 0285 |
| Pb92Sn8(Sb) | 280-305 | 350-450 | Triangular bars | 8/10x400 | 0.2 | EL03 0262 |
| Bi50Pb31.3Sn.18.7 | 96 | 150-180 | Wire | 2/3x400 | 0.2 | EL03 0192 |

Deoxidisation tablets, lead free, bottled 50 tablets EL13 0042

Deoxidisation tablets, lead free, bottled 800 tablets EL13 0043

Deoxidisation tablets (for solder baths with or without lead)

- To reduce dross formation
- The oxidation of the solder is slowed down by a very thin protective layer
- Recommended dosage: 3 to 5 tablets for every 10 kgs solder

Picture: Deoxidisation tablets delivery forms



Bottle 50 tablets



Bottle 800 tablets

Picture: Bars and Ingots delivery forms



Triangular bars



Extruded bars



Ingots



Highlight

Solder Bars, Triangular Bars and Ingots



- all alloys with or without lead
- highest purity, virgin grade
- excellent soldering and wetting properties
- minimal oxides
- minimal dross generation
- also available as microalloyed (SAC) SC



ELSOLD® Bars and Ingots, lead-free

| Alloy | Melting Range [°C] | Operation tem- perature [°C] | | | Weight [ca. kg] | Order number | |
|------------------|-----------------------|---------------------------------|-----------------|-----------|--------------------|--------------|--|
| Sn99.3Cu0.7 | 227 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 0351 | |
| Sn99.3Cu0.7 MA | 227 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 6005 | |
| Sn99.3Cu0.7P | 227 | 255-400 | Triangular bars | 8/10x400 | 0.2 | EL04 0358 | |
| Sn96.5Ag3Cu0.5 | 217-219 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 0403 | |
| Sn96.5Ag3Cu0.5 | 217-219 | 255-285 | Ingots | 20x20x335 | 1.0 | EL04 6001 | |
| Sn95.5Ag3.8Cu0.7 | 217 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 0374 | |
| Sn95.5Ag3.8Cu0.7 | 217 | 255-285 | Ingots | 50x20x490 | 3.0 | EL04 0406 | |
| Sn97Ag3 | 221-232 | 255-285 | Ingots | 50x20x490 | 3.0 | EL04 0397 | |
| Sn96.5Ag3.5 | 221 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 0156 | |
| Sn96.2Ag3.8 | 221-238 | 255-285 | Ingots | 50x18x600 | 4.0 | EL04 0411 | |
| Sn96.2Ag3.8 | 221-238 | 255-285 | Triangular bars | 8/10x400 | 0.2 | EL04 0389 | |
| Sn96Ag4 | 221-238 | 255-285 | Ingots | 50x20x490 | 3.0 | EL04 0419 | |
| Sn96.5Ag3.5P | 221 | 255-320 | Ingots | 50x20x490 | 3.0 | EL04 0408 | |

- ELSOLD® alloys comply with standards DIN EN 29453, DIN EN 61190-1-3 and ELSOLD® own standards
- further forms available upon request, such as thick and wide rods, flat tapes, thin rods and bars, threads, solid wires etc.
- all alloys can be supplied in deoxidised form on request

All lead-free alloys are available as ELSOLD® MA® (micro-alloyed)

Your advantages: • fine-grained structure facilitates visual inspection

- low erosion of copper allows lead-free tinning of thin wires and circuit paths, multiple joints and repairs
- Significant cost saving though low chemical attack on material soldering tips and equipment



ELSOLD® Solid Wires

Modern manufacturing technology, e.g. selective soldering, demands ultimate quality solid wires by using virgin grade base metals. ELSOLD® produces solid wires of highest purity. We guarantee consistent best product quality! Ongoing quality control of each and every production lot is recorded and filed. Our customers including the European Aerospace industry can fully rely on ELSOLD®, we are the only approved supplier of solid soft solder material with ECCS certification. (see page 2 ELSOLD® Certification).

Our modern production process permits the manufacture of all required alloys with or without lead and alloys for low and high temperature and also solder alloys for static baths for soft soldering processes in all areas of the electronic industry.

ELSOLD® Solid wires with lead

| Alloy | Melting Range [°C] | Operation tempe- rature [°C] | Ø [mm] | Weight [ca. kg] | Order number |
|--------------------------|-----------------------|---------------------------------|-----------|--------------------|--------------|
| Sn63Pb37 | 183 | 240-260 | 3 | 4 | EL05 1055 |
| Sn63Pb37P | 183 | 240-260 | 6 | 10 | EL05 6018 |
| Sn63Pb37P | 183 | 240-260 | 3 | 1 | EL05 0911 |
| Sn64Pb36P | 183 | 240-260 | 3 | 1 | EL05 0991 |
| Sn60Pb39.86Cu0.14P (HTF) | 183-190 | 240-260 | 1.5 | 1 | EL05 0527 |
| Pb95Sn3Ag2P | 304-310 | > 450 | 3 | 1 | EL05 0960 |

The list above shows a selection of our most sought-after products. Of course you can order the alloy you require.

All standard alloys are also available as solid wire

- Diameters available up to 8.0 mm
- Special dimensions available on request
- Standard coil sizes: 250 g $\,/$ 500 g / 1 kg / 4 kg / 10 kg / 25 kg

Picture: Solid wires with lead delivery forms





10 kg

25 kg



Solid wire



- all alloys with or without lead
- highest purity, virgin grade
- excellent soldering and wetting properties
- minimal oxides
- minimal dross generation
- also available as microalloyed (SAC) SC



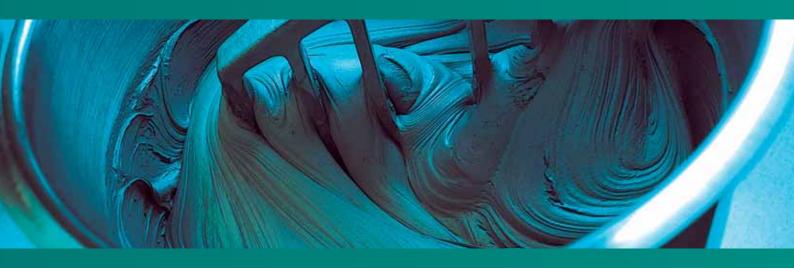
ELSOLD® Lead-free solid wires

| Alloy | Melting Range [°C] | Operation tempe- rature [°C] | Ø [mm] | Weight [ca. kg] | Order number |
|------------------|-----------------------|---------------------------------|-----------|--------------------|--------------|
| Sn99.3Cu0.7 | 227 | 255-285 | 3 | 5 | EL06 1023 |
| Sn99.3Cu0.7 | 227 | 255-285 | 1.5 | 1 | EL06 1039 |
| Sn99.3Cu0.7 MA | 227 | 255-285 | 1.5 | 1 | EL06 0006 |
| Sn97Cu3 | 230-250 | 255-285 | 3 | 5 | EL06 0598 |
| Sn97Cu3 | 230-250 | 255-285 | 6 | 15 | EL06 1086 |
| Sn97Ag3 | 221-232 | 255-285 | 2 | 2.5 | EL06 1012 |
| Sn96.5Ag3.5 | 221 | 255-285 | 1.2 | 2.5 | EL06 1067 |
| Sn96.2Ag3.8 | 221-238 | 255-285 | 2 | 4 | EL06 1076 |
| Sn96.5Ag3Cu0.5 | 217-219 | 255-285 | 3 | 4 | EL06 6019 |
| Sn96.5Ag3Cu0.5 | 217-219 | 255-285 | 6 | 10 | EL06 6003 |
| Sn95.8Ag3.5Cu0.7 | 217 | 255-285 | 3 | 4 | EL06 6023 |
| Sn95.5Ag3.8Cu0.7 | 217 | 255-285 | 3 | 4 | EL06 1034 |
| Sn95.5Ag3.8Cu0.7 | 217 | 255-285 | 2 | 5 | EL06 1029 |

All lead-free alloys are available as ELSOLD® MA® (micro-alloyed)

Your advantages: • fine-grained structure facilitates visual inspection

- low erosion of copper allows lead-free tinning of thin wires and circuit paths, multiple joints and repairs
- Significant cost saving though low chemical attack on material soldering tips and equipment



ELSOLD® Solder Paste

ELSOLD® solder paste particularly stands out due to excellent wetting behaviour over a wide range of temperature profiles. At the same time, the solder paste not only has best slump characteristics but also excellent adhesion. Storage and durability is not critical because it is a special and modified synthetic material. Further advantages: minimal shrin-

king, high printing speeds, high activity on all surfaces, useful for high speed printing. Repeatability, constant and excellent printing results, PCB by PCB.

ELSOLD® solder paste is suitable for closed rakel systems as well as for Fine Pitch printing.

ELSOLD® Solder Paste with lead

| Alloy | Metal content [%] | Powder size [µm] | Melting range [°C] | Packaging | Weight [g] | Flux type | Order number |
|----------------------|-------------------------|------------------------|--------------------------|-----------|---------------|------------|--------------|
| Sn63Pb37 | 90 | 25-45 | 183 | Cartridge | 1200 | SM-388 | EL07 0352 |
| Sn63Pb37 | 90 | 25-45 | 183 | Can | 250 | NWS-4200 | EL07 0485 |
| Sn63Pb37 | 90 | 25-45 | 183 | Can | 500 | AP-10 | EL07 0348 |
| Sn63Pb37 | 90 | 25-45 | 183 | Cartridge | 600 | AP-10 | EL07 0503 |
| Sn62Pb36Ag2 | 87 | 25-45 | 179 | Syringe | 35 | AP-10 | EL07 0330 |
| Sn62Pb36Ag2 | 90 | 25-45 | 179 | Can | 250 | AP-10 | EL07 0502 |
| Sn62Pb36Ag2 | 90 | 25-45 | 179 | Cartridge | 1200 | SM-388 | EL07 0002 |
| Sn62Pb36Ag2 | 87.5 | 25-45 | 179 | Can | 500 | AP-10 | EL07 0506 |
| Sn62Pb36Ag2 | 90 | 25-45 | 179 | Can | 500 | NC-559 AS | EL07 0404 |
| Sn62Pb36Ag2 | 88 | 25-45 | 179 | Can | 500 | NC-559 AS | EL07 0483 |
| Sn62Pb36Ag2 | 87 | 25-45 | 179 | Syringe | 100 | NC-559 AS | EL07 0482 |
| Sn62Pb36Ag2 | 90 | 25-45 | 179 | Can | 500 | RMA-223 AS | EL07 0428 |
| Sn62Pb36Ag2 | 90 | 25-45 | 179 | Can | 250 | NWS-4200 | EL07 0439 |
| Pb92.5Sn5Ag2.5 | 90 | 25-45 | 287-296 | Can | 250 | AP-10 | EL07 0507 |
| Sn62Pb36Ag2/Sn63Pb37 | 90 | 25-45 | 179-183 | Cartridge | 1200 | SM-388 | EL07 0356 |

- Flux classification as per DN EN 61190-1-1
- Available powder types: 3 / 4 / 5 / 6 on request
- Various metal levels available depending on the required viscosity

Delivery forms: Syringes 10 cc / 30 cc Cans 250 g / 500 g

Cartridges 600 g / 1.2 kg

Pro-Flow Cassettes 750 g

Picture: Solder Paste delivery forms







Cans



Pro-Flow Cassettes



NEW! LF Solder Paste AP-20



- Grain size T3 [45μm] up to T6 [15μm]
- non-corrosive residues, halogen-free
- excellent wetting properties in air and nitrogen atmosphere
- stable viscosity for more than 70 days at room temperature
- Tack Time > 48 hours, high thermal stability



ELSOLD® Solder Paste, lead-free

| Alloy | Metal content [%] | Powder size [µm] | Melting range [°C] | Packaging | Weight [g] | Flux type | Order number |
|------------------------------|-------------------------|------------------------|--------------------------|-----------|---------------|------------|--------------|
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | Cartridge | 1200 | SM-388 | EL08 0339 |
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | Can | 500 | SM-388 | EL08 0333 |
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | Can | 500 | Syntech-LF | EL08 0357 |
| Sn96.5Ag3Cu0.5 | 87.5 | 15-25 | 217-219 | Can | 500 | AP-20 | EL08 0016 |
| Sn96.5Ag3Cu0.5 | 88 | 05-15 | 217-219 | Can | 500 | AP-20 | EL08 0023 |
| Sn96.5Ag3Cu0.5 | 88.5 | 25-45 | 217-219 | Can | 500 | AP-20 | EL08 0011 |
| Sn96.5Ag3Cu0.5 | 86 | 25-45 | 217-219 | Syringe | 35 | SM-388 | EL08 0363 |
| Sn96.5Ag3Cu0.5 | 86 | 25-45 | 217-219 | Syringe | 100 | SM-388 | EL08 0603 |
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | Can | 500 | AP-20 | EL08 0007 |
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | Cartridge | 1200 | SM-388 | EL08 0339 |
| Sn96.5Ag3Cu0.5 (MA) | 88 | 20-38 | 217-219 | Can | 500 | AP-20 | EL08 0020 |
| Sn95.5Ag3.8Cu0.7 | 88 | 25-45 | 217 | Can | 500 | SM-388 | EL08 0009 |
| Sn99.3Cu0.7 | 88 | 25-45 | 227 | Can | 500 | AP-20 | EL08 0508 |
| Sn96.5Ag3Cu0.5 / Bi58Sn42 | 87 | 25-45 | 188-192 | Syringe | 100 | SM-388 | EL08 0608 |
| Bi57Sn42Ag1 | 86.5 | 25-45 | 139 | Syringe | 35 | AP-10 | EL08 0602 |

All lead-free alloys are available as ELSOLD® MA® (micro-alloyed)

- Your advantages: fine-grained structure facilitates visual inspection
 - low de-alloying of copper allows lead-free tinning of thin wires and circuit paths, multiple joints and repairs
 - Significant cost saving though low chemical attack on material soldering tips and equipment
 - excellent printing properties, for standard and high speed applications (Chip shooter)



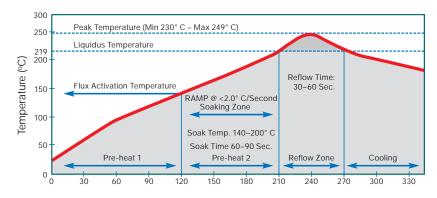


LF Solder Paste "Advanced Paste 40" [AP-40]

- storing at constant room temperature
- stable viscosity for more than 3 months at room temperature
- high durability (open time) for more than 72h at room temperature
- Tack Time > 5 days, at room temperature

- micro alloyed (SAC) SC
- Grain size T3 [45µm] to T6 [15µm]
- non-corrosive residues, halide-free
- excellent wetting properties in air and nitrogen atmosphere

| Alloy | Metal content [%] | Powder size [µm] | Melting range [°C] | Packaging | Weight [g] | FI type | ux class |
|---------------------|-------------------------|------------------------|--------------------------|--------------|---------------|------------|---------------|
| Sn96.5Ag3Cu0.5 | 88 | 25-45 | 217-219 | *see deliver | y forms | AP-40 | REL0 |
| Sn96.5Ag3Cu0.5 | 86 | 25-45 | 217-219 | *see deliver | y forms | AP-40 | REL0 |
| Sn96.5Ag3Cu0.5 (MA) | 88 | 20-38 | 217-219 | *see deliver | ry forms | AP-40 | REL0 |
| Sn95.5Ag3.8Cu0.7 | 88 | 25-45 | 217 | *see deliver | ry forms | AP-40 | REL0 |
| Sn99.3Cu0.7 | 88 | 25-45 | 227 | *see deliver | y forms | AP-40 | REL0 |



- Flux classification as per DN EN 61190-1-1
- Available powder types: 3 / 4 / 5 / 6 on request
- Various metal levels available depending on the required viscosity

Picture: Solder Paste delivery forms

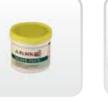
*Delivery forms: Syringes 10 cc / 30 cc Cans 250 g / 500 g Cartridges 600 g / 1.2 kg Pro-Flow Cassettes 750 g



Syringes and

Cartridges







Cans Pro-Flow Cassettes



ELSOLD® Flux

ELSOLD® supplies a complete range of high-quality fluxes, specially manufactured to meet the toughest industry requirements. In addition to the solder alloy, the most important factor in ensuing a soldering process of a consistently high quality is the flux.

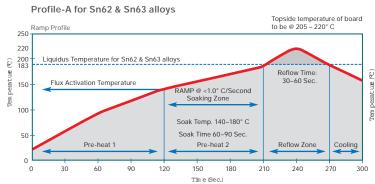
It must prepare the surface to be soldered for the actual soldering process as well promote wetting. Furthermore, following soldering the flux should have largely evaporated - without leaving behind any resistance-lowering or corrosive residues on the circuit boards.

ELSOLD® Paste Flux - Tacky Flux

The pasty fluxes (Tacky Flux) from ELSOLD ® are suitable for a wide range of applications in electronics manufacturing. Pasty fluxes combine the advantags of SMD adhesives and fluxes. Thanks to their good adhesive properties the components are held in position until the soldering process. The fluxes ere effective with existing solder depots, however additional solder can also be introduced, e.g. in wire form.

Our fluxes can be applied by means of dispensers, screen or template printing as well as by immersion or tampon and brush application. The flux is highly adhesive, has excellent wetting properties, a broad process window and a high degree of compatibility with all standard circuit board surfaces. It is also perfect for all "rework applications".

| Flux | Flux type | DIN EN 61190-1-1 | Packaging [cc] | Application | Order number |
|----------|---------------|---------------------|----------------|---------------------------------------|--------------|
| AP-10 | no clean | ROM1 | 10 | Lead and high lead content solder | EL09 0040 |
| AP-20 | no clean | REL0 | 10 | Lead-free solder, especially reliable | EL09 0057 |
| NC 559AS | no clean | REL0 | 10 | especially light residue | EL09 0032 |
| SM 388 | no clean | REL0 | 10 | Lead-free & lead-containing processes | EL09 0039 |
| NWS 4200 | water soluble | REM0 | 10 | Can be washed off with water | EL09 0006 |



300 Peak Temperature (Min 230° C – Max 249° C) 250 Liquidus Temperature Reflow Time Flux Activation Temperature 30-60 Sec 150 RAMP @ <2.0° C/Second Soaking Zone 100 Soak Temp. 140-200° C Soak Time 60-90 Sec Pre-heat 2 Reflow Zone 180 300

Picture: Flux delivery form

Delivery forms: Syringes 10 cc / 30 cc Cans 90 g / 180 g Cartridges 150 g





Syringes and Cartridges

Cans



• ELSOLD® **Flux**

| Flux | Contai- ner [I] | Solid con- tent [%] | Flux Basis | Flux Basis | DIN EN 61190-1-1 | Application | Order number |
|--------------------|--------------------|------------------------|--------------------------------|-----------------------------|---------------------|---|-----------------|
| 1003NC | 10 | 5.9 | Rosin-free Organic | Solvent- based | ORL0 | Tinning of cables in dip soldering process | EL10 0055 |
| 1004NC | 20 | 2.0 | Rosin-free Organic | Solvent- based | ORL0 | Tinning of cables in dip soldering process, General electronics | EL10 0108 |
| 2000NC | 20 | 2.9 | Contains rosin, Organic | Solvent- based | ORL0 | General electronics | EL10 0040 |
| 2000M NC | 20 | 2.9 | Contains rosin, Organic | Solvent- based | ORL0 | General electronics, Automotive electronics Telecom; standard and lead-free solder alloys | EL10 0110 |
| 2001NC | 20 | 2.6 | Contains rosin, Organic | Solvent- based | ORL0 | Wave soldering of lead-free alloys. Low residue level. | EL10 0116 |
| 2001NC | 10 | 2.6 | Contains rosin, Organic | Solvent- based | ORL0 | Wave soldering of lead-free alloys. Low residue level. | EL10 0115 |
| 2001M NC | 20 | 1.9 | Organic | Solvent- based | ORL0 | General electronics | EL10 0013 |
| 3002M NC | 20 | 2.9 | Organic | Water- based VOC-free | ORL0 | General electronics, Automotive electronics, Telecom; standard and lead-free solder alloys, Sprayflux | EL10 0109 |
| 3003NC | 20 | 2.9 | Organic | Water- based VOC-free | ORL0 | Wave soldering of lead-free alloys. Low residue level. | EL10 0117 |
| Flussmittel 045 | 10 | 17/45 | Rosin- based | Solvent- based | ROL0 | General electronics | EL10 0091 |
| Flussmittel 110 | 20 | 6.2 | Contains rosin, | Solvent- based | ORL0 | General wave soldering | EL10 0002 |
| Flussmittel 177 | 10 | 45 | Contains rosin, | Solvent- based | ROL0 | General electronics | EL10 0003 |
| Flussmittel 356 | 20 | 17 | Rosin- based halide-free | Solvent- based | ROL0 | General electronics, drag soldering, dip soldering, wave soldering of printed circuit boards | EL10 0006 |





Rework Flux Solutions!

ELSOLD supplies a complete range of high-quality fluxes, specially manufactured to meet the toughest industry requirements.

In addition to the solder alloy, the most important factor to ensure a solder rework process of a consistent and reliable quality is the flux. It must prepare the surface to be soldered for the actual rework process and promote proper wetting.

Furthermore, following reflow the flux should have evaporated without leaving any resistance-lowering or corrosive residues on the circuit boards.



| → ELSOLD® Rework Flux | | | | | | | |
|-----------------------|------------------|-------------|-------------------|--------------|--|--|--|
| Name | DIN EN 61190-1-1 | Acid number | Packaging | Order number | | | |
| ELSOLD® 200R | ORL0 | 24 mg KOH/g | Flux Pen | EL10 0078 | | | |
| ELSOLD® 200R | ORL0 | 24 mg KOH/g | Flux Bottle 25 ml | EL10 0079 | | | |
| ELSOLD® 400R | ROL0 | 70 mg KOH/g | Flux Pen | EL10 0080 | | | |
| ELSOLD® 400R | ROL0 | 70 mg KOH/g | Flux Bottle 25 ml | EL10 0081 | | | |

| Test Method | Test Results | IPC-Test Method |
|----------------------------|--------------|--------------------|
| Copper Mirror Test | Pass | IPC-TM-650 2.3.32 |
| Silver Chromate Paper Test | Pass | IPC-TM-650 2.3.33 |
| Halide, quantitative | 0,0% | IPC-TM-650 2.3.35 |
| SIR Test | Pass | IPC-TM-650 2.6.3.3 |
| Corrosion Test | Pass | IPC-TM-650 2.6.15 |

Picture: Rework Flux delivery forms



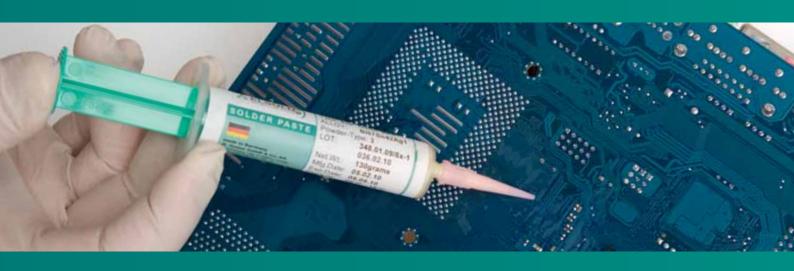
Flux Pen



Flux Pen, Flux Bottle



Flux Bottles



Rework Flux Solutions!



The pasty fluxes from ELSOLD® (gel flux / tacky flux) like AP 40, are suitable for a wide range of rework applications. Pasty fluxes combine the advantages of SMD* adhesives and fluxes. Due to this fact the components are held in position until the rework process is finished. The fluxes are effective with existing solder depots as well as the separate dispensing of solder. The flux is highly adhesive, has excellent wetting properties, a broad process latitu-

de and a high degree of compatibility with all standard circuit board surfaces e.g. perfect for Rework-Applications. This applies to leaded and lead free alloys and processes.

* SMD-Surface Mounted Device

| → ELSOLD® Pasty Rework Flux | | | | | | | |
|------------------------------------|-------------------------|-------------------|-----------------|--------------|--|--|--|
| Name | DIN EN 61190-1-1 | Viscosity | Packaging | Order number | | | |
| ELSOLD® AP-40 | REL0 | 150 Pa.s | Syringe 5 ccm | EL09 0003 | | | |
| ELSOLD® AP-40 | REL0 | 150 Pa.s | Syringe 10 ccm | EL09 0012 | | | |
| ELSOLD® AP-40 | REL0 | 150 Pa.s | Jar 250 ccm | EL09 0013 | | | |
| ELSOLD® FRA-01 | Flux remover for printe | ed circuit boards | Spray can 0.4 l | EL12 0003 | | | |

| Test Method | Test Results | IPC-Test Method |
|----------------------------|--------------|--------------------|
| Copper Mirror Test | Pass | IPC-TM-650 2.3.32 |
| Silver Chromate Paper Test | Pass | IPC-TM-650 2.3.33 |
| Halide, quantitative | 0,0% | IPC-TM-650 2.3.35 |
| SIR Test | Pass | IPC-TM-650 2.6.3.3 |
| Corrosion Test | Pass | IPC-TM-650 2.6.15 |

Picture: Pasty Rework Flux delivery forms



Syringe 5 ccm & Syringe 10 ccm



Refill jars



ELSOLD® Cleaner Spray cans





New Flux for the Solar Industry

- particularely developed for solar module production
- all fluxes are halide-free
- approved by notable manufacturers



• ELSOLD® Flux - Solar Industry

| Flussmittel | Container [1] | Solid con- tent [%] | Product description | Product description | DIN EN 61190-1-1 | Use | Order number |
|-------------|------------------|------------------------|-----------------------|---------------------|---------------------|---|--------------|
| 1004S | 10 | 2 | Rosin-free Organic | Solvent- based | ORL0 | Soldering processes in the solar industry | EL11 0119 |
| 2001S | 10 | 1.7 | Organic | Solvent- based | ORL0 | Soldering processes in the solar industry | EL11 0120 |
| 3003S | 10 | 2 | Rosin-free Organic | Water- based | ORL0 | Soldering processes in the solar industry | EL11 0121 |

Picture: Delivery forms Flux



20 I canister



10 I canister



5 I canister



ELSOLD® Cleaner

PCB cleaning or the cleaning of populated circuit boards involves the removal of flux residue from circuit boards, hybrids and DCBs. Although the so called "no clean" procedure has established itself for numerous production processes in the low-end sector, cleaning, espacially in the case of high-end subassembies, is still indispensable. Based on our years of experience, we are able to supply our customers with a complete program of cleaning agents for the cleaning of subassemblies, templates and tools as well as DCBs and power modules. With our globally leading cleaning agents - aqueos, solvent-based and aqueous-alkaline - you will find the best, most economical and environmentally friendly solution for all your processes.

They can remove, amongst other things, flux from lead based soldering, solder paste from templates, burnt-in flux in soldering machines and soldering carriers, adhesive residue and thick-film paste. the cleaning process is often unavoidable and forms the basis for further production steps-It assists in preventing errors, e.g. during wire bonding and the bonding of molded chips. Furthermore, you can prevent paste printing errors, corrosion, electrochemical migration and creepage current, as well as avoiding the contamination of subassemblies in the soldering machines.

Through the use of modern ELSOLD [®] cleaning products the above named problems can be solved, i.e. avoided right from the start.

ELSOLD® Cleaner

| Cleaner | Container | Content [1] | Product basis | Application | Order number |
|---------|--|-------------|---|------------------------|--------------|
| WBI-01 | Plastic container | 5.0 | Water-based cleaner with corrosion inhibitor | Ultrasound | EL12 0001 |
| WXS-01 | Plastic container | 5.0 | Water-based cleaner for temp- lates, carriers and PCBs | Ultrasound/ rinsing | EL12 0002 |
| FRA-01 | Spray can | 0.4 | Flux remover for printed circuit boards | manual | EL12 0003 |
| SSC-01 | Spray bottle | 0.5 | Screen and template cleaner | manual | EL12 0004 |
| SSW-01 | Plastic container with cleaning cloths | 100 Pcs. | Screen and template cleaning cloths | manual | EL12 0005 |

Picture: Cleaner delivery forms



Cleaning cloths



Spray cans



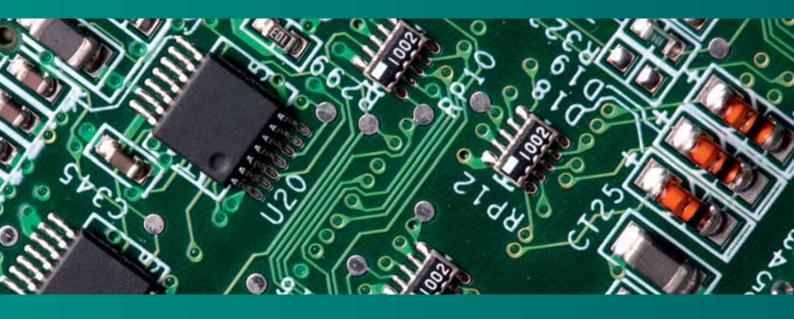
Spry bottles



5 I containers

Adress/Delivery adress Company Phone Fax Street Email Postal Code / ZIP Author City Country Your Order Copy Send away Fill in +49 (0) 53 21 754-222 Fax **Email** info@elsold.de Order number Product description Quantity EL____ EL____ EL__ ___ We would like to receive samples of the following products Order number Product description Quantity City, Date Name in capital letters Signature





Address ELSOLD GmbH & Co. KG

Postfach 2129 D-38611 Goslar

Im Schleeke 108 D-38640 Goslar

Phone

Germany +49 (0) 53 21 754-229 International +49 (0) 53 21 754-235 +49 (0) 53 21 754-238

Telefax +49 (0) 53 21 754-222

Email info@elsold.com

www.elsold.com

Distribution partner